

IGBT

SGL25N120RUF

Short Circuit Rated IGBT

General Description

Fairchild's RUF series of Insulated Gate Bipolar Transistors (IGBTs) provides low conduction and switching losses as well as short circuit ruggedness. The RUF series is designed for applications such as motor control, uninterrupted power supplies (UPS) and general inverters where short circuit ruggedness is a required feature.

Features

- Short circuit rated 10 μ s @ T_C = 100°C, V_{GE} = 15V
- · High speed switching
- Low saturation voltage : $V_{CE(sat)} = 2.3 \text{ V } @ \text{ I}_{C} = 25 \text{A}$
- High input impedance

Applications

AC & DC motor controls, general purpose inverters, robotics, and servo controls.





Absolute Maximum Ratings $T_C = 25^{\circ}C$ unless otherwise noted

Symbol	Description		SGL25N120RUF	Units	
V _{CES}	Collector-Emitter Voltage		1200	V	
V _{GES}	Gate-Emitter Voltage		± 25	V	
	Collector Current	$@ T_C = 25^{\circ}C$	40	А	
I _C	Collector Current	@ T _C = 100°C	25	А	
I _{CM (1)}	Pulsed Collector Current		75	А	
	Short Circuit Withstand Time	@ T _C = 100°C	10	μs	
T _{SC} P _D	Maximum Power Dissipation	$@ T_C = 25^{\circ}C$	270	W	
	Maximum Power Dissipation	@ T _C = 100°C	108	W	
T _J	Operating Junction Temperature		-55 to +150	°C	
T _{stg}	Storage Temperature Range		-55 to +150	°C	
T _L	Maximum Lead Temp. for soldering Purposes, 1/8" from case for 5 seconds		300	°C	

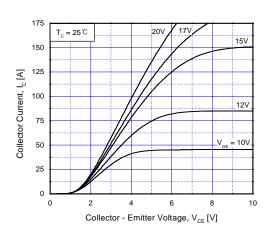
Notes:

(1) Repetitive rating : Pulse width limited by max. junction temperature

Thermal Characteristics

Symbol	Parameter	Тур.	Max.	Units
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case		0.46	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient		25	°C/W

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Units
Off Cha	racteristics					
BV _{CES}	Collector-Emitter Breakdown Voltage	$V_{GE} = 0V, I_C = 1mA$	1200			V
ΔB _{VCES} / ΔΤ _J	Temperature Coefficient of Breakdown Voltage	$V_{GE} = 0V, I_C = 1mA$		0.6		V/°C
I _{CES}	Collector Cut-Off Current	$V_{CE} = V_{CES}, V_{GE} = 0V$			1	mA
I _{GES}	G-E Leakage Current	$V_{GE} = V_{GES}, V_{CE} = 0V$			± 100	nA
On Char	racteristics					
V _{GE(th)}	G-E Threshold Voltage	$I_C = 25 \text{mA}, V_{CE} = V_{GE}$	3.5	5.5	7.5	V
	Collector to Emitter	$I_C = 25A$, $V_{GE} = 15V$		2.3	3.0	V
$V_{CE(sat)}$	Saturation Voltage	$I_C = 40A$, $V_{GE} = 15V$		2.8		V
Dvnami	c Characteristics	, , , , , , , , , , , , , , , , , , , ,				
C _{ies}	Input Capacitance	$V_{CE} = 30V, V_{GE} = 0V,$		2400		pF
C _{oes}	Output Capacitance	f = 1MHz		220		pF
C _{res}	Reverse Transfer Capacitance	_ · - ······2		70		pF
td(on)	Turn-On Delay Time			30		ns
t _r .	Rise Time			60		ns
t _{d(off)}	Turn-Off Delay Time	$V_{CC} = 600 \text{ V}, I_{C} = 25\text{A},$		70	130	ns
t _f	Fall Time	$R_G = 10\Omega$, $V_{GE} = 15V$,		150	300	ns
E _{on}	Turn-On Switching Loss	Inductive Load, T _C = 25°C		1.60		mJ
E _{off}	Turn-Off Switching Loss			1.63		mJ
E _{ts}	Total Switching Loss			3.23	4.55	mJ
t _{d(on)}	Turn-On Delay Time			30		ns
t _r	Rise Time			70		ns
t _{d(off)}	Turn-Off Delay Time	$V_{CC} = 600 \text{ V}, I_C = 25\text{A},$		90	165	ns
t _f	Fall Time	$R_G = 10\Omega, V_{GE} = 15V,$		200	400	ns
E _{on}	Turn-On Switching Loss	Inductive Load, T _C = 125°C		1.88		mJ
E _{off}	Turn-Off Switching Loss			2.50		mJ
E _{ts}	Total Switching Loss			4.35	6.31	mJ
T _{sc}	Short Circuit Withstand Time	$V_{CC} = 600 \text{ V}, V_{GE} = 15 \text{V}$ @ $T_C = 100 ^{\circ}\text{C}$	10			μs
Q_g	Total Gate Charge	V 600 V I 25A		110	165	nC
Q _{ge}	Gate-Emitter Charge	$V_{CE} = 600 \text{ V}, I_{C} = 25\text{A},$ $V_{GE} = 15\text{V}$		18	27	nC
Q_{gc}	Gate-Collector Charge	vGE - 10 v		55	83	nC
	Internal Emitter Inductance	Measured 5mm from PKG		18		nΗ



Common Emitter

V_{GE} = 15V

T_C = 25°C

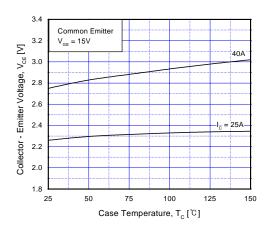
T_C = 125°C

T_C = 15°C

T_C = 15°

Fig 1. Typical Output Characteristics

Fig 2. Typical Saturation Voltage Characteristics



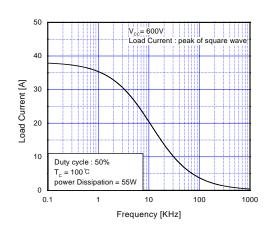
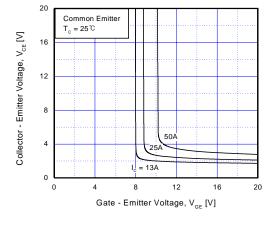


Fig 3. Saturation Voltage vs. Case Temperature at Variant Current Level

Fig 4. Load Current vs. Frequency



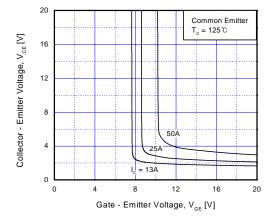


Fig 5. Saturation Voltage vs. V_{GE}

Fig 6. Saturation Voltage vs. $V_{\rm GE}$

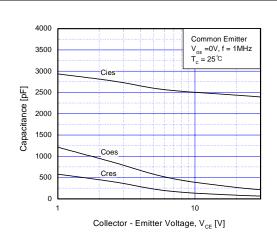


Fig 7. Capacitance Characteristics

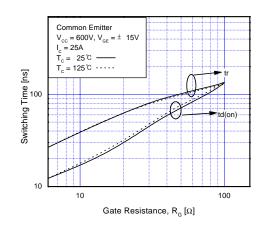


Fig 8. Turn-On Characteristics vs.
Gate Resistance

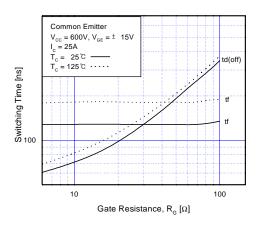


Fig 9. Turn-Off Characteristics vs.
Gate Resistance

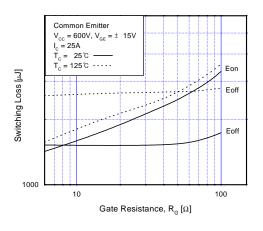


Fig 10. Switching Loss vs. Gate Resistance

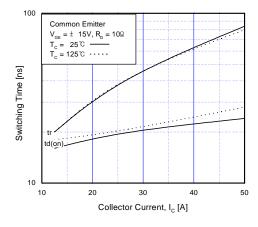


Fig 11. Turn-On Characteristics vs. Collector Current

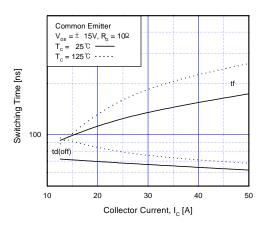
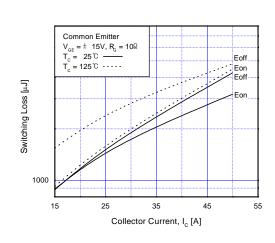


Fig 12. Turn-Off Characteristics vs. Collector Current



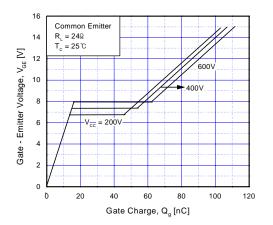
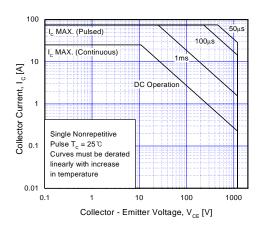


Fig 13. Switching Loss vs. Collector Current

Fig 14. Gate Charge Characteristics



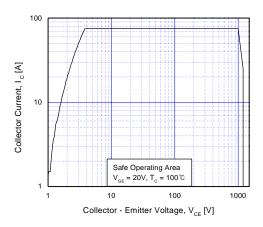


Fig 15. SOA Characteristics

Fig 16. Turn-Off SOA

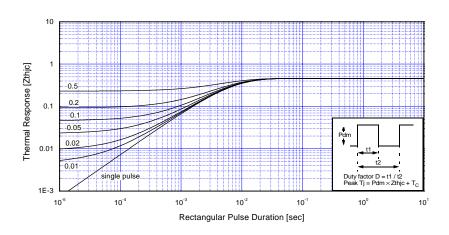
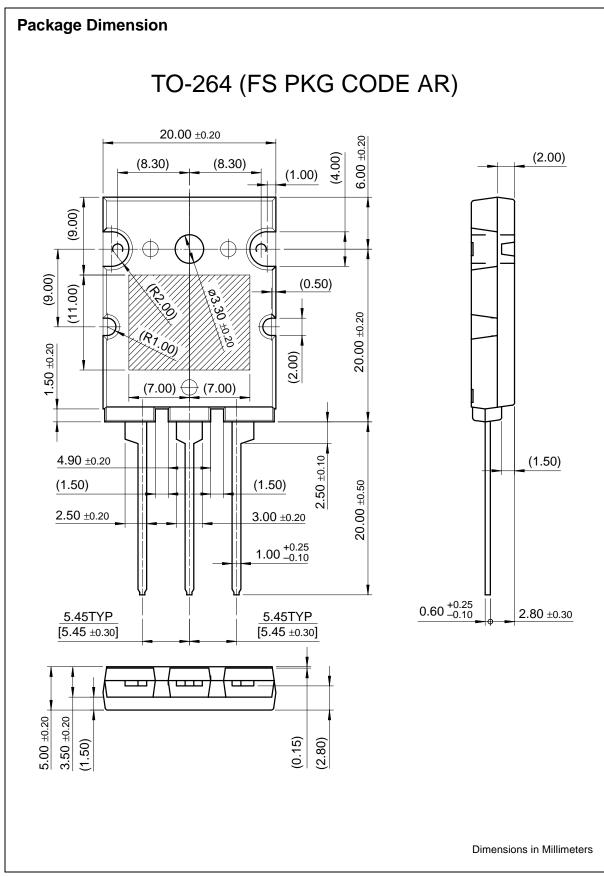


Fig 17. Transient Thermal Impedance of IGBT



TRADEMARKS

The following are registered and unregistered trademarks Fairchild Semiconductor owns or is authorized to use and is not intended to be an exhaustive list of all such trademarks.

ACEx TM Bottomless TM CoolFET TM CROSSVOLT TM DenseTrench TM DOME TM EcoSPARK TM E ² CMOS TM EnSigna TM	FAST® FASTr™ FRFET™ GlobalOptoisolator™ GTO™ HiSeC™ I²C™ ISOPLANAR™ LittleFET™	MICROWIRETM OPTOLOGICTM OPTOPLANARTM PACMANTM POPTM Power247TM PowerTrench® QFETTM QSTM	SLIENT SWITCHER® SMART STARTTM SMPTM STAR*POWERTM StealthTM SuperSOTTM-3 SuperSOTTM-6 SuperSOTTM-8 SyncFETTM	UHC™ UltraFET [®] VCX™
		~. <u>-</u> .	The state of the s	

STAR*POWER is used under license

DISCLAIMER

FAIRCHILD SEMICONDUCTOR RESERVES THE RIGHT TO MAKE CHANGES WITHOUT FURTHER NOTICE TO ANY PRODUCTS HEREIN TO IMPROVE RELIABILITY, FUNCTION OR DESIGN. FAIRCHILD DOES NOT ASSUME ANY LIABILITY ARISING OUT OF THE APPLICATION OR USE OF ANY PRODUCT OR CIRCUIT DESCRIBED HEREIN; NEITHER DOES IT CONVEY ANY LICENSE UNDER ITS PATENT RIGHTS, NOR THE RIGHTS OF OTHERS.

LIFE SUPPORT POLICY

FAIRCHILD'S PRODUCTS ARE NOT AUTHORIZED FOR USE AS CRITICAL COMPONENTS IN LIFE SUPPORT DEVICES OR SYSTEMS WITHOUT THE EXPRESS WRITTEN APPROVAL OF FAIRCHILD SEMICONDUCTOR CORPORATION.

As used herein:

- 1. Life support devices or systems are devices or systems which, (a) are intended for surgical implant into the body, or (b) support or sustain life, or (c) whose failure to perform when properly used in accordance with instructions for use provided in the labeling, can be reasonably expected to result in significant injury to the user.
- 2. A critical component is any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

PRODUCT STATUS DEFINITIONS

Definition of Terms

Datasheet Identification	Product Status	Definition
Advance Information	Formative or In Design	This datasheet contains the design specifications for product development. Specifications may change in any manner without notice.
Preliminary	First Production	This datasheet contains preliminary data, and supplementary data will be published at a later date. Fairchild Semiconductor reserves the right to make changes at any time without notice in order to improve design.
No Identification Needed	Full Production	This datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice in order to improve design.
Obsolete	Not In Production	This datasheet contains specifications on a product that has been discontinued by Fairchild semiconductor. The datasheet is printed for reference information only.

©2002 Fairchild Semiconductor Corporation Rev. H5



back to top

Product status/pricing/packaging

Product	Product status	Pricing*	Inventory check & ordering	Package type	Leads	Packing method
SGL25N120RUFTU	Full Production	\$7.58	Purchase	<u>TO-264</u>	3	RAIL

^{*} Fairchild 1,000 piece Budgetary Pricing

back to top

<u>Home</u> | <u>Find products</u> | <u>Technical information</u> | <u>Buy products</u> | <u>Support</u> | <u>Company</u> | <u>Contact us</u> | <u>Site index</u> | <u>Privacy policy</u>

© Copyright 2002 Fairchild Semiconductor